

Economy Primary Side Controller

FEATURES

- User Programmable Soft Start With Active Low Shutdown
- User Programmable Maximum Duty Cycle
- Accessible 5V Reference
- Undervoltage Lockout
- Operation to 1MHz
- 0.4A Source/0.8A Sink FET Driver
- Low 100 μ A Startup Current

DESCRIPTION

The UCC3809 family of BCDMOS economy low power integrated circuits contains all the control and drive circuitry required for off-line and isolated DC-to-DC fixed frequency current mode switching power supplies with minimal external parts count. Internally implemented circuits include undervoltage lockout featuring startup current less than 100 μ A, a user accessible voltage reference, logic to ensure latched operation, a PWM comparator, and a totem pole output stage to sink or source peak current. The output stage, suitable for driving N-Channel MOSFETs, is low in the off state.

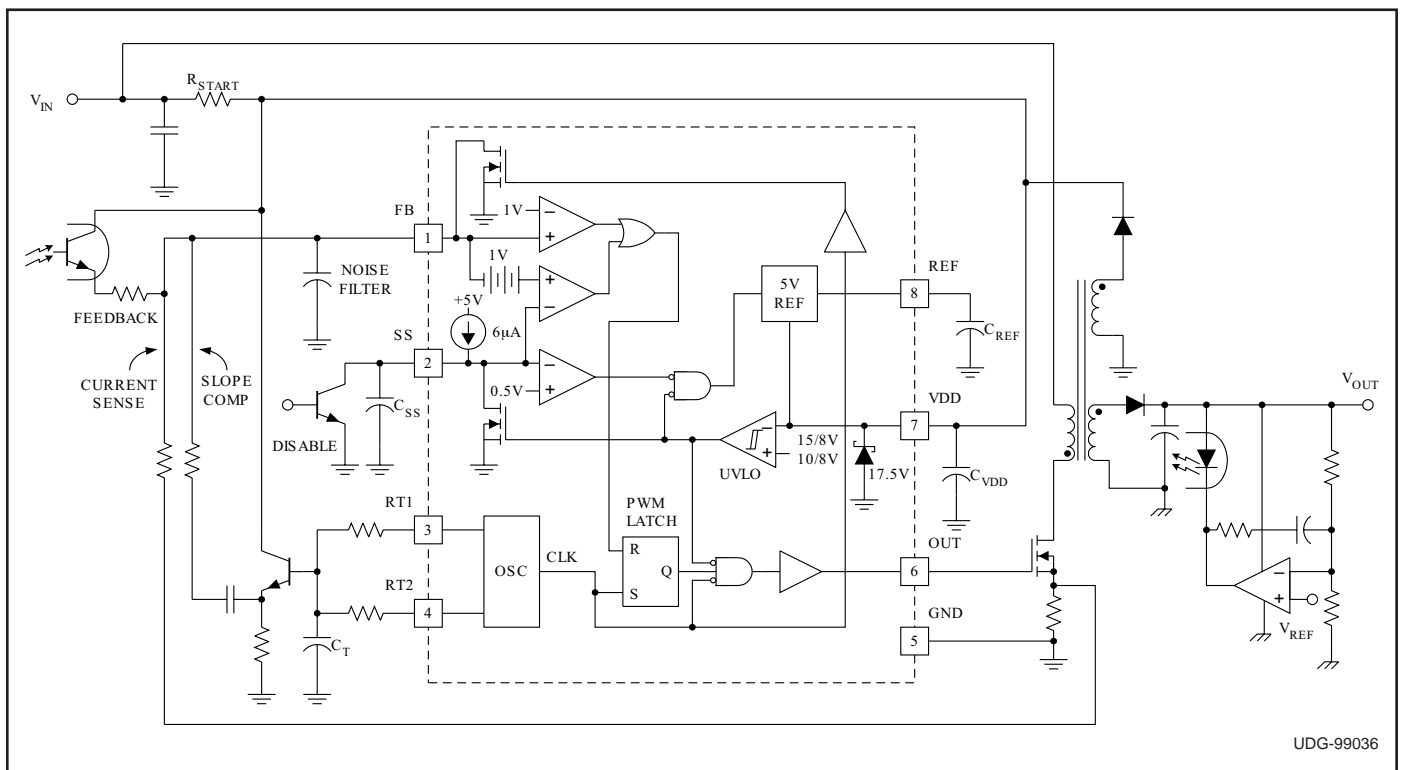
Oscillator frequency and maximum duty cycle are programmed with two resistors and a capacitor. The UCC3809 family also features full cycle soft start.

The family has UVLO thresholds and hysteresis levels for off-line and DC-to-DC systems as shown in the table to the left.

PART NUMBER	TURN ON THRESHOLD	TURN OFF THRESHOLD
UCCX809-1	10V	8V
UCCX809-2	15V	8V

The UCC3809 and the UCC2809 are offered in the 8 pin SOIC (D), PDIP (N), TSSOP (PW), and MSOP (P) packages. The small TSSOP and MSOP packages make the device ideal for applications where board space and height are at a premium.

TYPICAL APPLICATION DIAGRAM



ABSOLUTE MAXIMUM RATINGS*

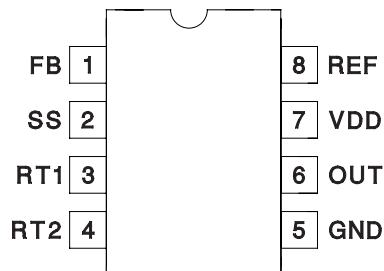
VDD	19V
I _{VDD}	25mA
I _{OUT} (tpw < 1μs and Duty Cycle < 10%)	−0.4A to 0.8A
RT1, RT2, SS	−0.3V to REF + 0.3V
I _{REF}	−15mA
Storage Temperature	−65°C to +150°C
Junction Temperature	−55°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C

* Values beyond which damage may occur.

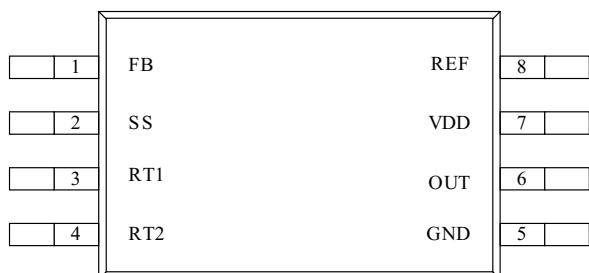
All voltages are with respect to ground unless otherwise stated. Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAM

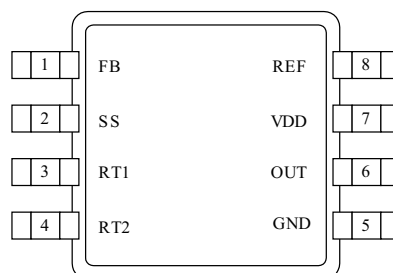
SOIC-8, DIL-8 (Top View) D, N and J Packages



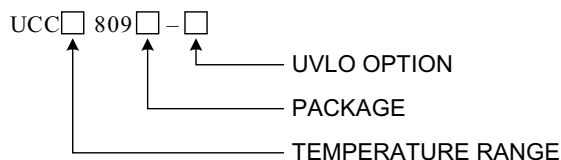
TSSOP-8 (Top View) PW Package



MSOP-8 (Top View) P Package



ORDERING INFORMATION



ELECTRICAL CHARACTERISTICS

Unless otherwise specified, C_{VREF} = 0.47 μF, VDD = 12V. T_A = T_J.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Supply Section					
VDD Clamp	I _{VDD} = 10mA	16	17.5	19	V
I _{VDD}	No Load		600	900	μA
I _{VDD} Starting	(Note 1)		110		μA
I _{VDD} Standby	UCCx809-1, VDD = Start Threshold - 300mV		110	125	μA
	UCCx809-2, VDD = Start Threshold - 300mV		130	170	μA
Undervoltage Lockout Section					
Start Threshold (UCCx809-1)		9.4		10.4	V
UVLO Hysteresis (UCCx809-1)		1.65			V
Start Threshold (UCCx809-2)		14.0		15.6	V
UVLO Hysteresis (UCCx809-2)		6.2			V
Voltage Reference Section					
Output Voltage	I _{REF} = 0mA	4.75	5	5.25	V
Line Regulation	VDD = 10V to 15V		2		mV
Load Regulation	I _{REF} = 0mA to 5mA		2		mV
Comparator Section					
I _{FB}	Output Off		−100		nA
Comparator Threshold		0.9	0.95	1	V
OUT Propagation Delay (No Load)	V _{FB} = 0.8V to 1.2V at T _R = 10ns		50	100	ns

ELECTRICAL CHARACTERISTICS Unless otherwise specified, $C_{VREF} = 0.47 \mu F$, $V_{DD} = 12V$, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Soft Start Section					
I_{SS}	$V_{DD} = 16V$, $V_{SS} = 0V$; $-40^\circ C$ to $+85^\circ C$	-4.9	-7.0	-9.1	μA
	$V_{DD} = 16V$, $V_{SS} = 0V$; $< -40^\circ C$; $> +85^\circ C$	-4.0	-7.0	-10.0	μA
V_{SS} Low	$V_{DD} = 7.5V$, $I_{SS} = 200\mu A$			0.2	V
Shutdown Threshold		0.44	0.48	0.52	V
Oscillator Section					
Frequency	$RT1 = 10k$, $RT2 = 4.32k$, $C_T = 820pF$	90	100	110	kHz
Frequency Change with Voltage	$V_{DD} = 10V$ to $15V$		0.1		%/V
C_T Peak Voltage			3.33		V
C_T Valley Voltage			1.67		V
C_T Peak to Peak Voltage		1.54	1.67	1.80	V
Output Section					
Output V_{SAT} Low	$I_{OUT} = 80mA$ (dc)		0.8	1.5	V
Output V_{SAT} High	$I_{OUT} = -40mA$ (dc), $V_{DD} - OUT$		0.8	1.5	V
Output Low Voltage During UVLO	$I_{OUT} = 20mA$ (dc)			1.5	V
Minimum Duty Cycle	$V_{FB} = 2V$		0		%
Maximum Duty Cycle			70		%
Rise Time	$C_{OUT} = 1nF$		35		ns
Fall Time	$C_{OUT} = 1nF$		18		ns

Note 1. Ensured by design. Not 100% production tested.

PIN DESCRIPTIONS

FB: This pin is the summing node for current sense feedback, voltage sense feedback (by optocoupler) and slope compensation. Slope compensation is derived from the rising voltage at the timing capacitor and can be buffered with an external small signal NPN transistor. External high frequency filter capacitance applied from this node to GND is discharged by an internal 250Ω on resistance NMOS FET during PWM off time and offers effective leading edge blanking set by the RC time constant of the feedback resistance from current sense resistor to FB input and the high frequency filter capacitor capacitance at this node to GND.

GND: Reference ground and power ground for all functions.

OUT: This pin is the high current power driver output. A minimum series gate resistor of 3.9Ω is recommended to limit the gate drive current when operating with high bias voltages.

REF: The internal 5V reference output. This reference is buffered and is available on the REF pin. REF should be bypassed with a $0.47\mu F$ ceramic capacitor.

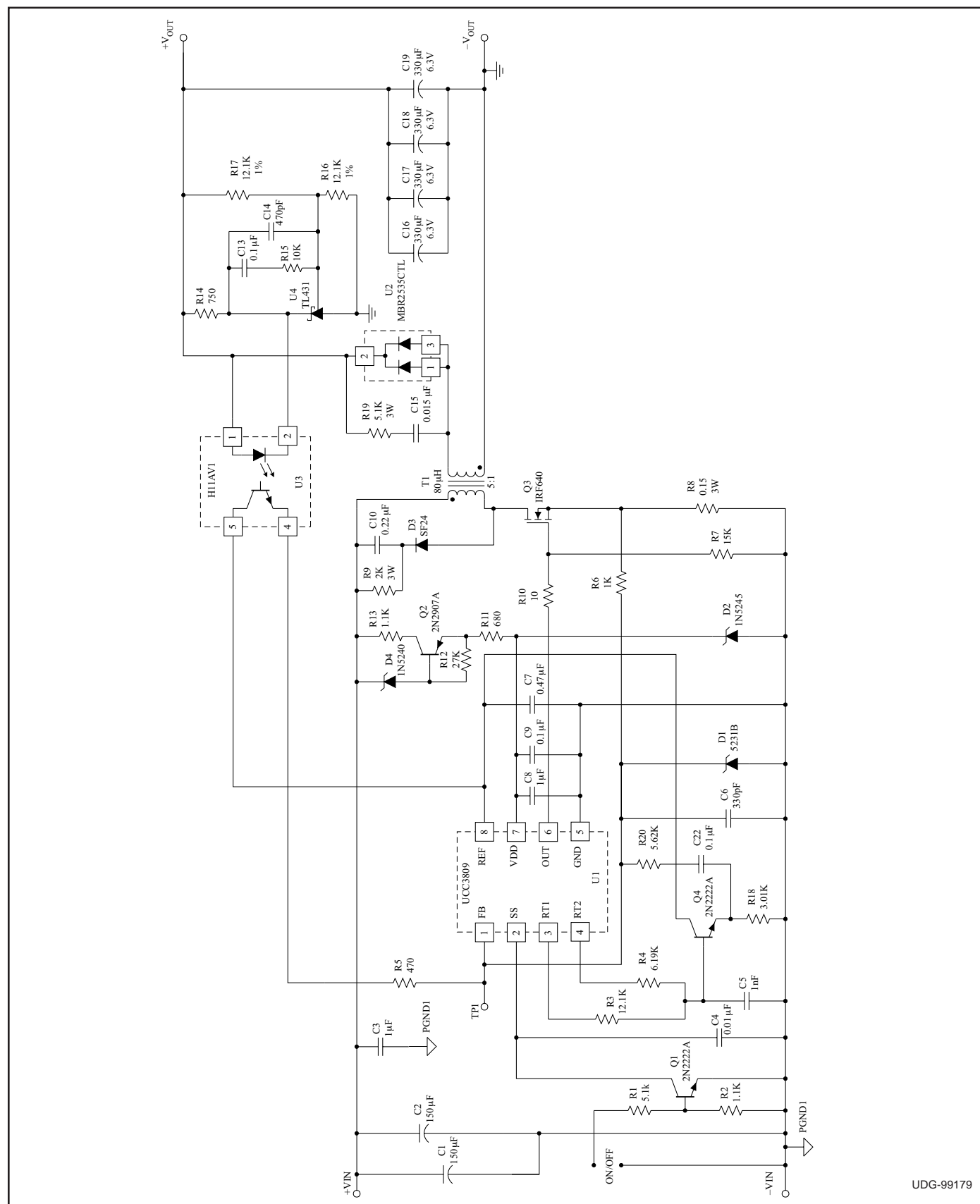
RT1: This pin connects to timing resistor $RT1$ and controls the positive ramp time of the internal oscillator ($T_r = 0.74 \cdot (C_T + 27pF) \cdot RT1$). The positive threshold of the internal oscillator is sensed through inactive timing resistor $RT2$ which connects to pin $RT2$ and timing capacitor C_T .

RT2: This pin connects to timing resistor $RT2$ and controls the negative ramp time of the internal oscillator ($T_f = 0.74 \cdot (C_T + 27pF) \cdot RT2$). The negative threshold of the internal oscillator is sensed through inactive timing resistor $RT1$ which connects to pin $RT1$ and timing capacitor C_T .

SS: This pin serves two functions. The soft start timing capacitor connects to SS and is charged by an internal $6\mu A$ current source. Under normal soft start SS is discharged to at least 0.4V and then ramps positive to 1V during which time the output driver is held low. As SS charges from 1V to 2V soft start is implemented by an increasing output duty cycle. If SS is taken below 0.5V, the output driver is inhibited and held low. The user accessible 5V voltage reference also goes low and $I_{VDD} < 100\mu A$.

VDD: The power input connection for this device. This pin is shunt regulated at 17.5V which is sufficiently below the voltage rating of the DMOS output driver stage. VDD should be bypassed with a $1\mu F$ ceramic capacitor.

APPLICATION INFORMATION



UDG-99179

Figure 1. Isolated 50W flyback converter utilizing the UCC3809. The switching frequency is 70kHz, $V_{in} = -32V$ to $-72V$, $V_{out} = +5V$, $I_{out} = 0A$ to $10A$

APPLICATION INFORMATION (cont.)

The Typical Application Diagram shows an isolated flyback converter utilizing the UCC3809. Note that the capacitors C_{REF} and C_{VDD} are local decoupling capacitors for the reference and IC input voltage, respectively. Both capacitors should be low ESR and ESL ceramic, placed as close to the IC pins as possible, and returned directly to the ground pin of the chip for best stability. REF provides the internal bias to many of the IC functions and C_{REF} should be at least $0.47\mu F$ to prevent REF from drooping.

FB Pin

The basic premise of the UCC3809 is that the voltage sense feedback signal originates from an optocoupler that is modulated by an external error amplifier located on the secondary side. This signal is summed with the current sense signal and any slope compensation at the FB pin and compared to a 1V threshold, as shown in the Typical Application Diagram. Crossing this 1V threshold resets the PWM latch and modulates the output driver on-time much like the current sense comparator used in the UC3842. In the absence of a FB signal, the output will follow the programmed maximum on-time of the oscillator.

When adding slope compensation, it is important to use a small capacitor to AC couple the oscillator waveform before summing this signal into the FB pin. By correctly selecting the emitter resistor of the optocoupler, the voltage sense signal can force the FB node to exceed the 1V threshold when the output that is being compared exceeds a desired level. Doing so drives the UCC3809 to zero percent duty cycle.

Oscillator

The following equation sets the oscillator frequency:

$$F_{OSC} = [0.74 \cdot (CT + 27pF) \cdot (RT1 + RT2)]^{-1}$$

$$D_{MAX} = 0.74 \cdot RT1 \cdot (CT + 27pF) \cdot F_{OSC}$$

Referring to Figure 2 and the waveforms in Figure 3, when Q1 is on, CT charges via the $R_{DS(on)}$ of Q1 and RT1. During this charging process, the voltage of CT is sensed through RT2. The S input of the oscillator latch, S(OSC), is level sensitive, so crossing the upper threshold (set at $2/3 V_{REF}$ or 3.33V for a typical 5.0V reference) sets the Q output (CLK signal) of the oscillator latch high. A high CLK signal results in turning off Q1 and turning on Q2. CT now discharges through RT2 and the $R_{DS(on)}$ of Q2. CT discharges from 3.33V to the lower threshold (set at $1/3 V_{REF}$ or 1.67V for a typical 5.0V

reference) sensed through RT1. The R input to the oscillator latch, R(OSC), is also level sensitive and resets the CLK signal low when CT crosses the 1.67V threshold, turning off Q2 and turning on Q1, initiating another charging cycle.

Figure 3 shows the waveforms associated with the oscillator latch and the PWM latch (shown in the Typical Application Diagram). A high CLK signal not only initiates a discharge cycle for CT, it also turns on the internal NMOS FET on the FB pin causing any external capacitance used for leading edge blanking connected to this pin to be discharged to ground. By discharging any external capacitor completely to ground during the external switch's off-time, the noise immunity of the converter is enhanced allowing the user to design in smaller RC components for leading edge blanking. A high CLK signal also sets the level sensitive S input of the PWM latch, S(PWM), high, resulting in a high output, Q(PWM), as shown in Figure 3. This Q(PWM) signal will remain high until a reset signal, R(PWM) is received. A high R(PWM) signal results from the FB signal crossing the 1V threshold, or during soft start or if the SS pin is disabled.

Assuming the UVLO threshold is satisfied, the OUT signal of the IC will be high as long as Q(PWM) is high and S(PWM), also referred to as CLK, is low. The OUT signal will be dominated by the FB signal as long as the FB signal trips the 1V threshold while CLK is low. If the FB signal does not cross the 1V threshold while CLK is low, the OUT signal will be dominated by the maximum duty cycle programmed by the user. Figure 3 illustrates the various waveforms for a design set up for a maximum duty cycle of 70%.

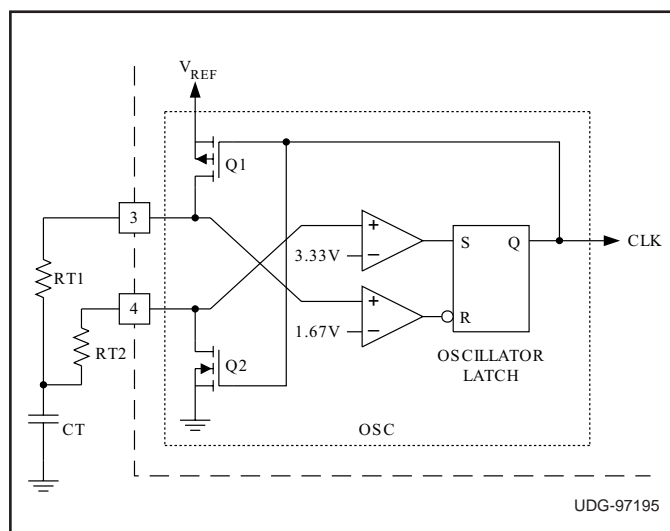


Figure 2. UCC3809 oscillator.

APPLICATION INFORMATION (cont.)

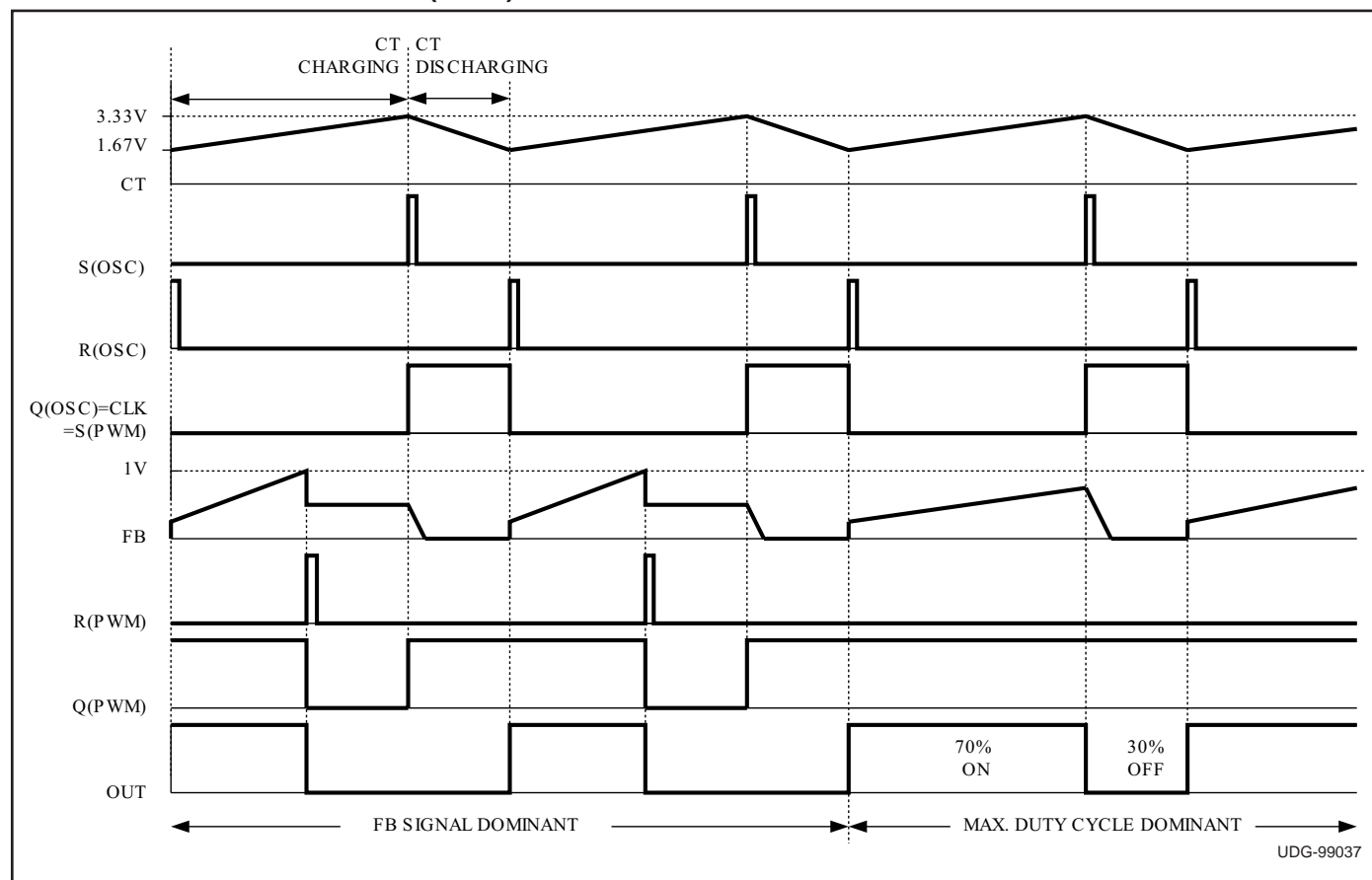


Figure 3. Waveforms associated with the oscillator latch and the PWM latch.

The recommended value for C_T is 1nF for frequencies in the 100 kHz or less range and smaller C_T for higher frequencies. The minimum recommended values of R_{T1} and R_{T2} are 10k Ω and 4.32k Ω , respectively. Using these values maintains a ratio of at least 20:1 between the $R_{DS(on)}$ of the internal FETs and the external timing resistors, resulting in minimal change in frequency over temperature. Because of the oscillator's susceptibility to capacitive coupling, examine the oscillator frequency by looking at the common R_{T1} - R_{T2} - C_T node on the circuit board as opposed to looking at pins 3 and 4 directly. For good noise immunity, R_{T1} and R_{T2} should be placed as close to pins 3 and 4 of the IC as possible. C_T should be returned directly to the ground pin of the IC with minimal stray inductance and capacitance.

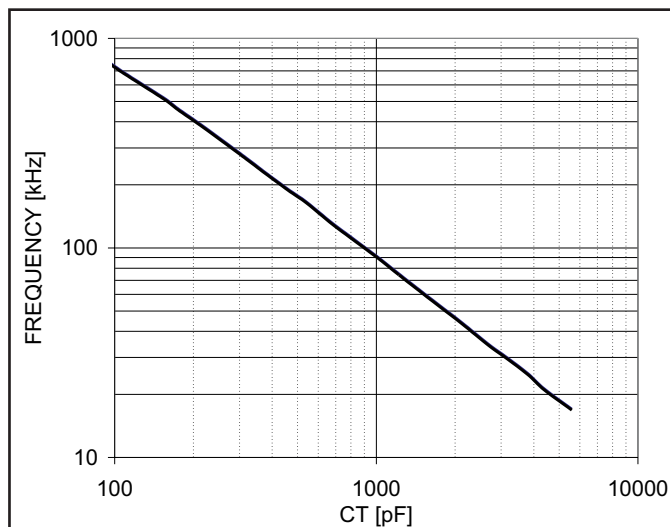


Figure 4. Oscillator frequency vs. C_T ($R_{T1} = 10k$, $R_{T2} = 4.32k$)

APPLICATION INFORMATION (cont.)

Synchronization

Both of the synchronization schemes shown in Figure 5 can be successfully implemented with the internal oscillator of the UCC3809. Both schemes allow access to the timing ramp needed for slope compensation and have minimal impact on the programmed maximum duty cycle. In the absence of a sync pulse, the PWM controller will run independently at the frequency set by RT1, RT2, and CT. This free running frequency must be approximately 15 to 20% lower than the sync pulse frequency to insure the free running oscillator does not cross the comparator threshold before the desired sync pulse.

Option I uses the synchronization pulse to pull pin 3 low, triggering the internal 1.67V comparator to reset the RS latch and initiate a charging cycle. The valley voltage of the CT waveform is higher when synchronized using this configuration, decreasing the ramp charge and discharge times, thereby increasing the operating frequency; otherwise the overall shape of the CT voltage waveform is un-

changed.

Option II uses the synchronization pulse to superimpose the sync voltage onto the peak of the CT waveform. This triggers the internal 3.33V comparator, initiating a discharge cycle. The sync pulse is summed with the free running oscillator waveform at the CT node, resulting in a spike on top of the CT peak voltage.

ADDITIONAL INFORMATION

Please refer to the following Unitrode application topics for additional information.

[1] Application Note U-165, Design Review: Isolated 50W Flyback Converter with the UCC3809 Primary Side Controller by Lisa Dinwoodie.

[2] Design Note DN-89, Comparing the UC3842, UCC3802, and UCC3809 Primary Side PWM Controllers by Lisa Dinwoodie.

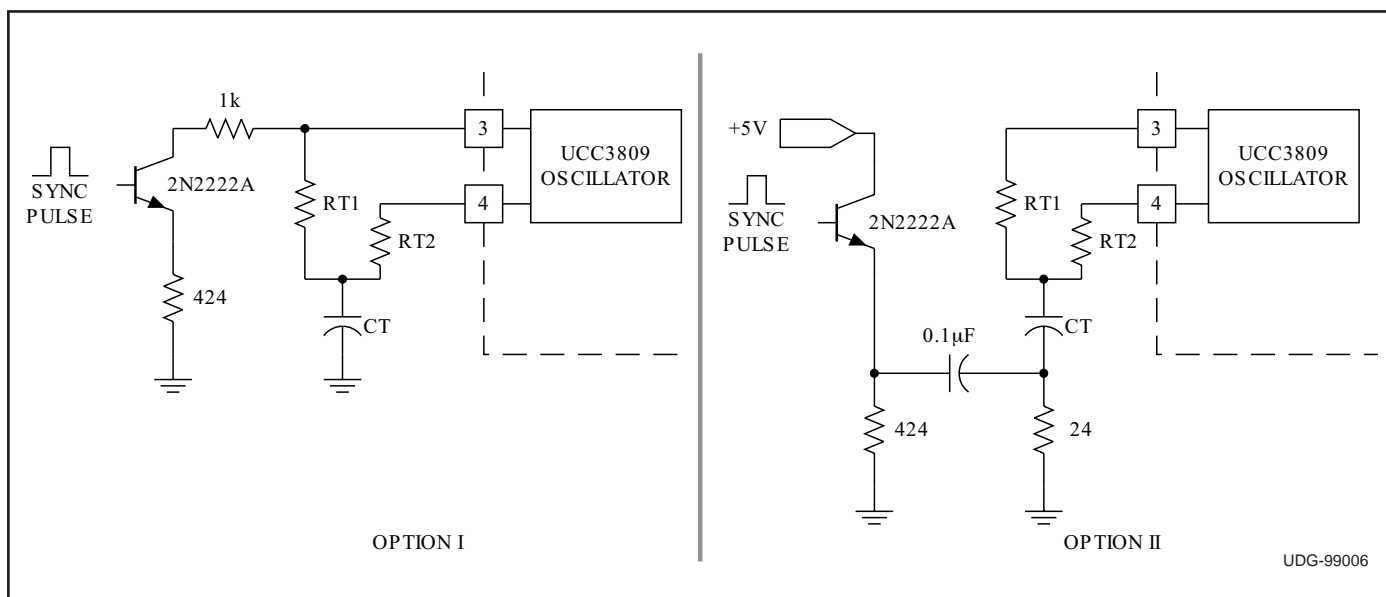


Figure 5. UCC3809 synchronization options.

TYPICAL CHARACTERISTICS CURVES

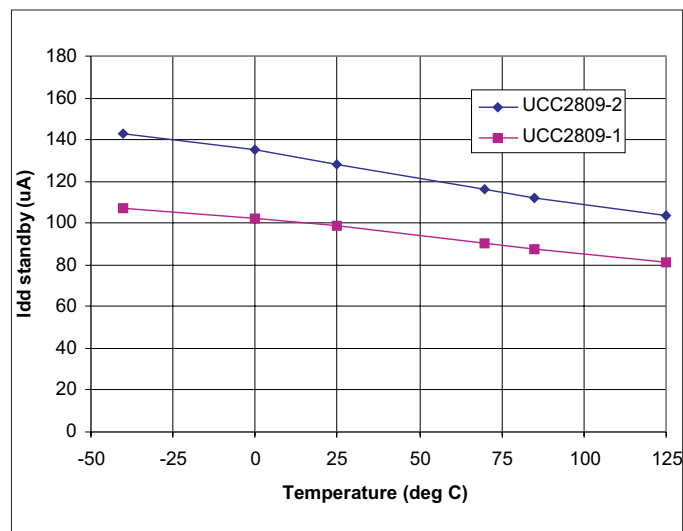


Figure 6. I_{DD} (standby) vs. temperature.

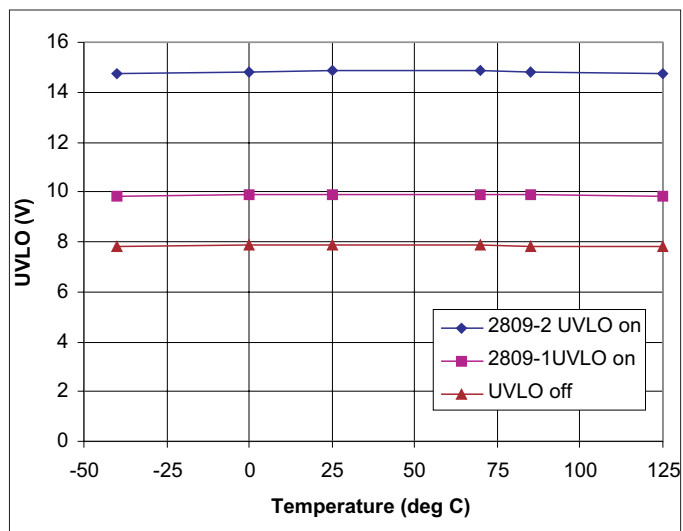


Figure 7. UVLO vs. temperature.

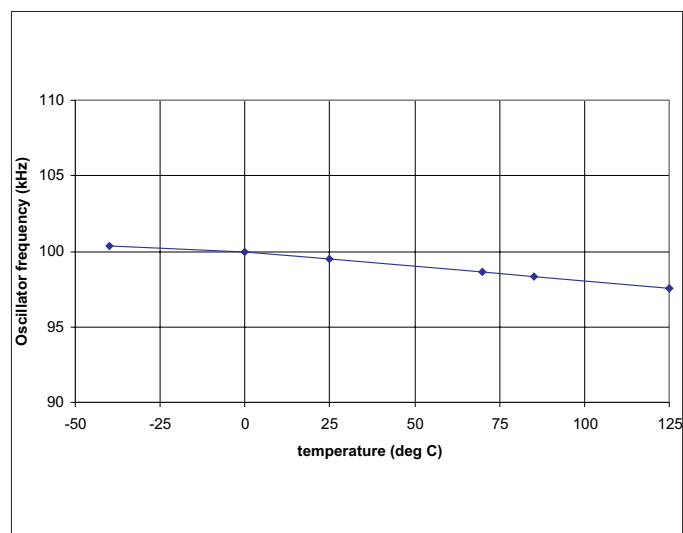


Figure 8. Oscillator frequency vs. temperature.

REVISION HISTORY

REV. B 11/04

Added I_{vdd} Stand-by Current specifications in the Electrical Characteristics table.

Modified I_{vdd} Starting specifications in the Electrical Characteristics table.

Added Typical Characteristics Curves for I_{dd}(Standby), UVLO thresholds, and Oscillator Frequency.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UCC2809D-1	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809D-1G4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809D-2	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809D-2G4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809DTR-1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809DTR-1G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809DTR-2	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809DTR-2G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC2809P-1	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809P-1G4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809P-2	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809P-2G4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PTR-1	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PTR-1G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PTR-2	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PTR-2G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PW-1	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR
UCC2809PW-1G4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR
UCC2809PW-2	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PW-2G4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PWTR-1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2809PWTR-1G4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809D-1	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809D-1G4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809D-2	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UCC3809D-2G4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809DTR-1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809DTR-1G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809DTR-2	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809DTR-2G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3809N-1	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC3809N-1G4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC3809N-2	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC3809N-2G4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC3809P-1	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809P-1G4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809P-2	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809P-2G4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PTR-1	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PTR-1G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PTR-2	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PTR-2G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PW-1	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PW-1G4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PW-2	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PW-2G4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PWTR-1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3809PWTR-1G4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

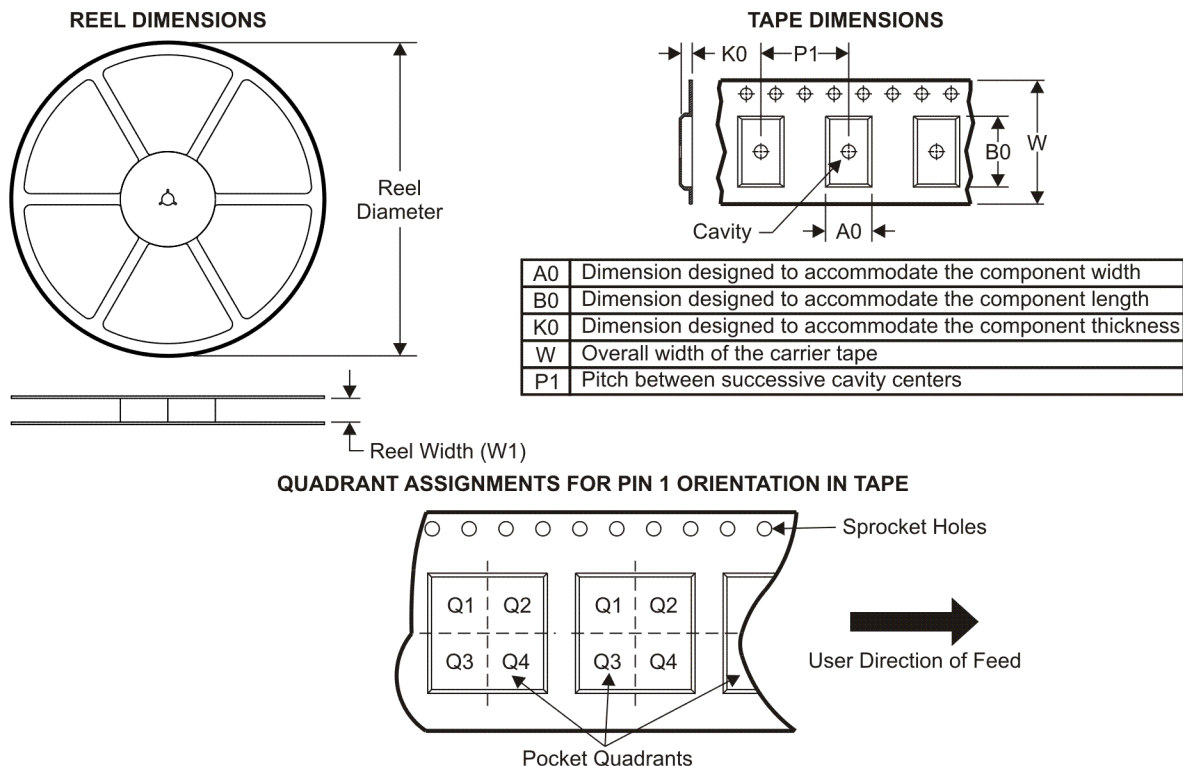
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC2809DTR-1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2809DTR-2	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2809PTR-1	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
UCC2809PTR-2	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
UCC2809PWTR-1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC3809DTR-1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3809DTR-2	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3809PTR-1	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
UCC3809PTR-2	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
UCC3809PWTR-1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC2809DTR-1	SOIC	D	8	2500	340.5	338.1	20.6
UCC2809DTR-2	SOIC	D	8	2500	340.5	338.1	20.6
UCC2809PTR-1	MSOP	DGK	8	2500	346.0	346.0	29.0
UCC2809PTR-2	MSOP	DGK	8	2500	346.0	346.0	29.0
UCC2809PWTR-1	TSSOP	PW	8	2000	346.0	346.0	29.0
UCC3809DTR-1	SOIC	D	8	2500	340.5	338.1	20.6
UCC3809DTR-2	SOIC	D	8	2500	340.5	338.1	20.6
UCC3809PTR-1	MSOP	DGK	8	2500	346.0	346.0	29.0
UCC3809PTR-2	MSOP	DGK	8	2500	346.0	346.0	29.0
UCC3809PWTR-1	TSSOP	PW	8	2000	346.0	346.0	29.0

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DGK (S-PDSO-G8)

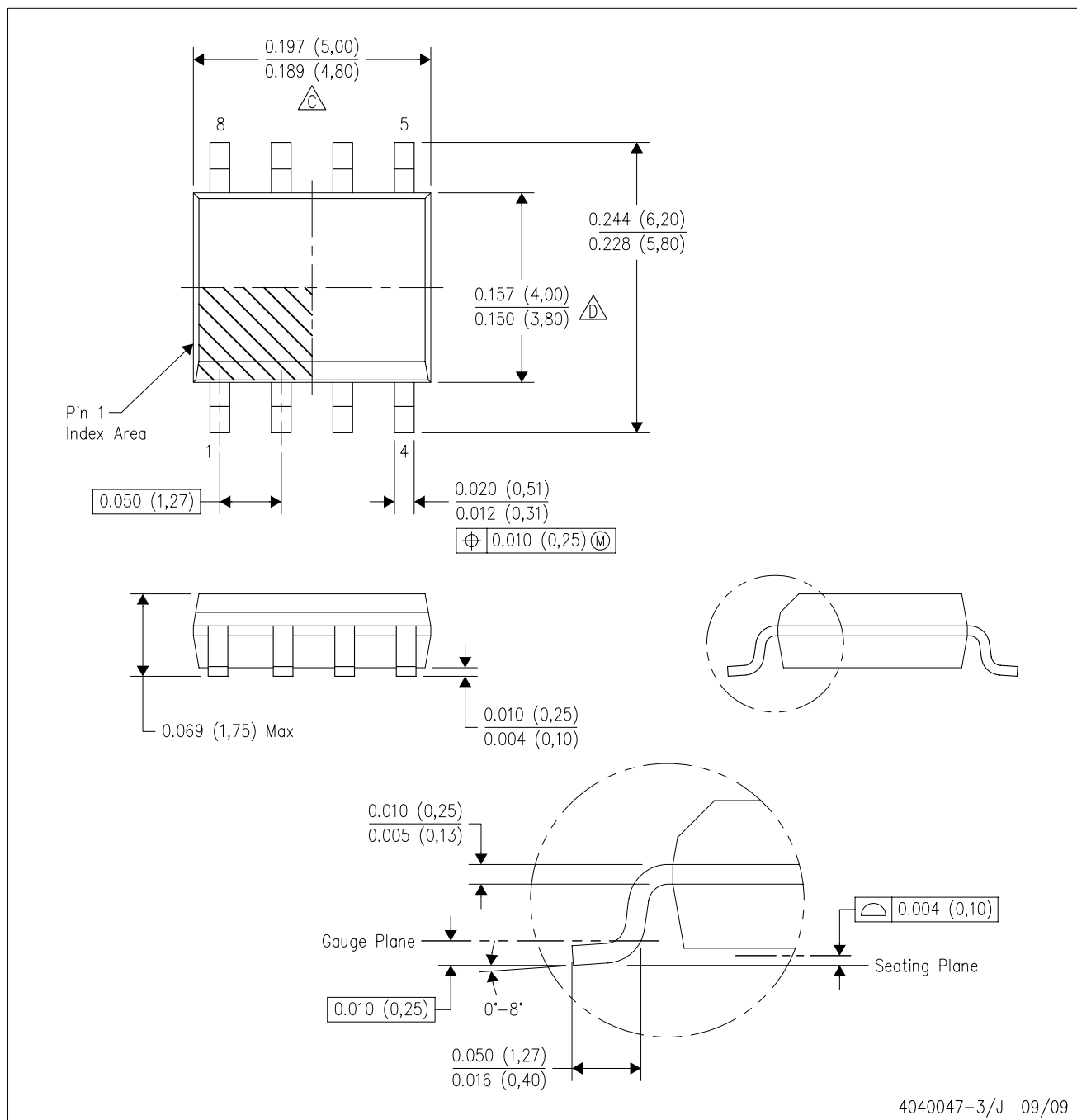
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/J 09/09

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2009, Texas Instruments Incorporated